



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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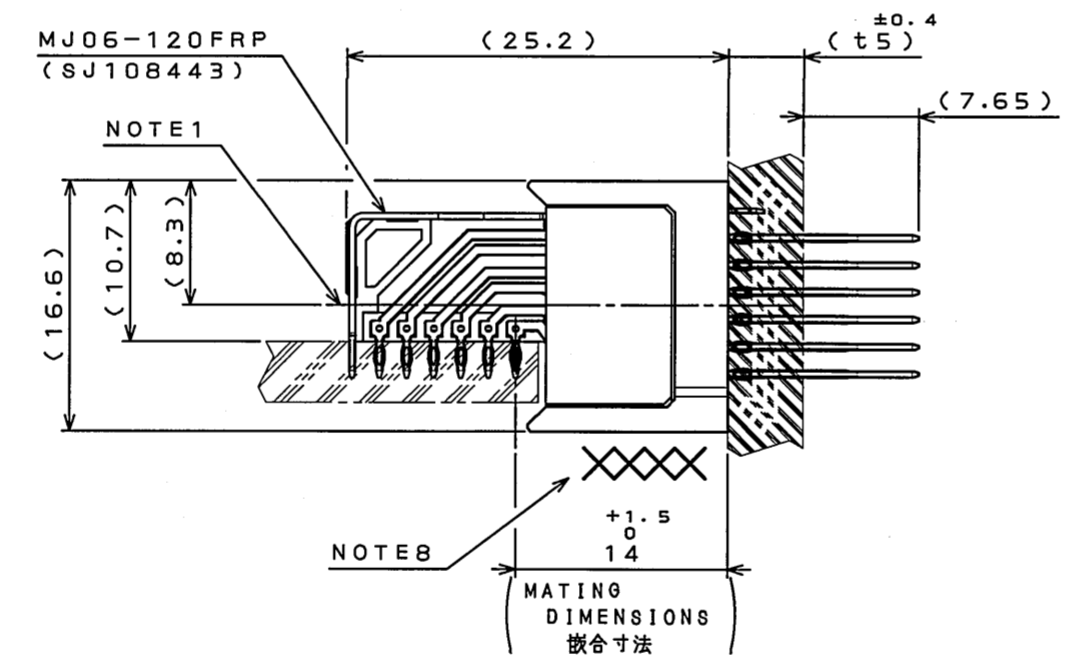
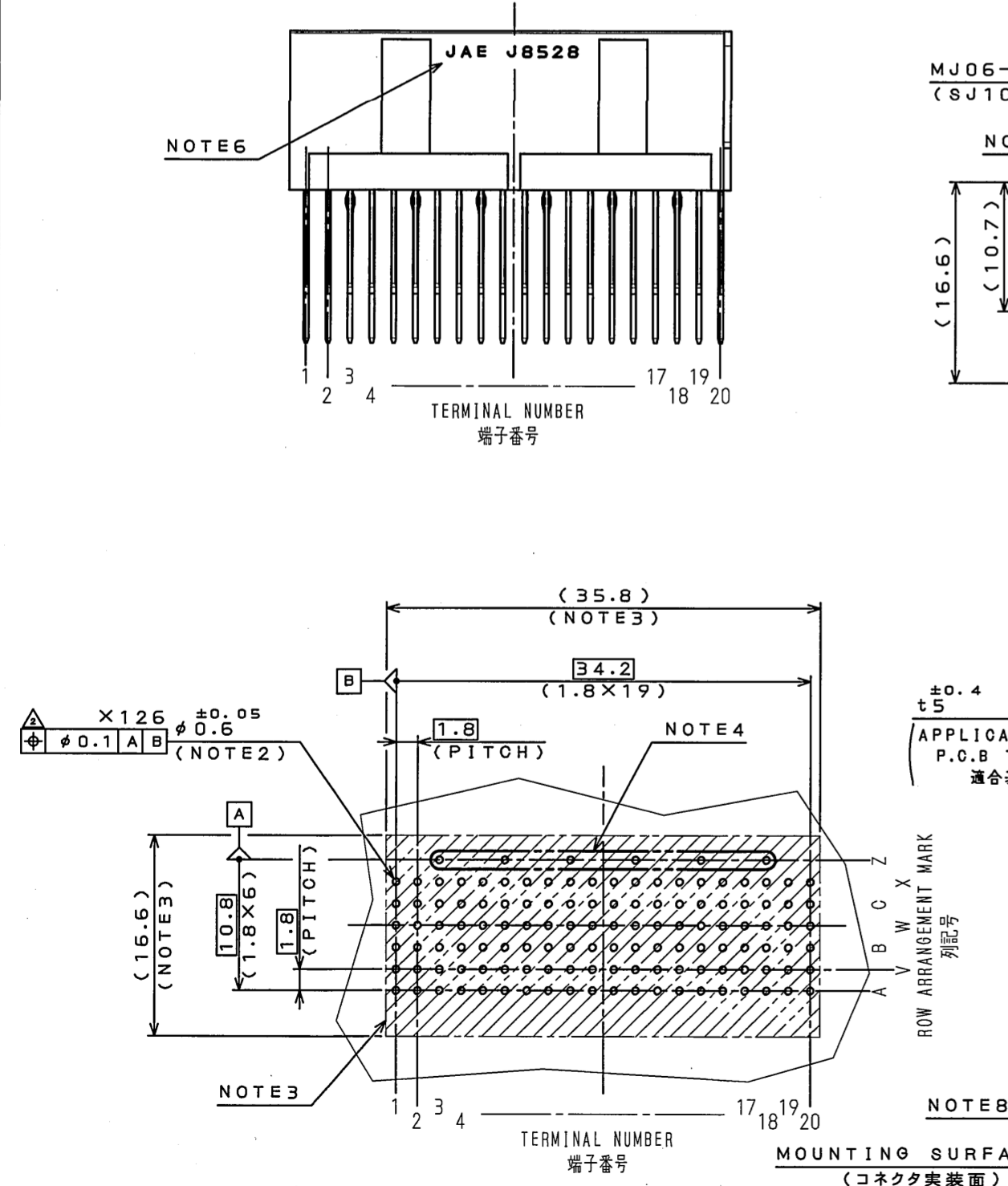
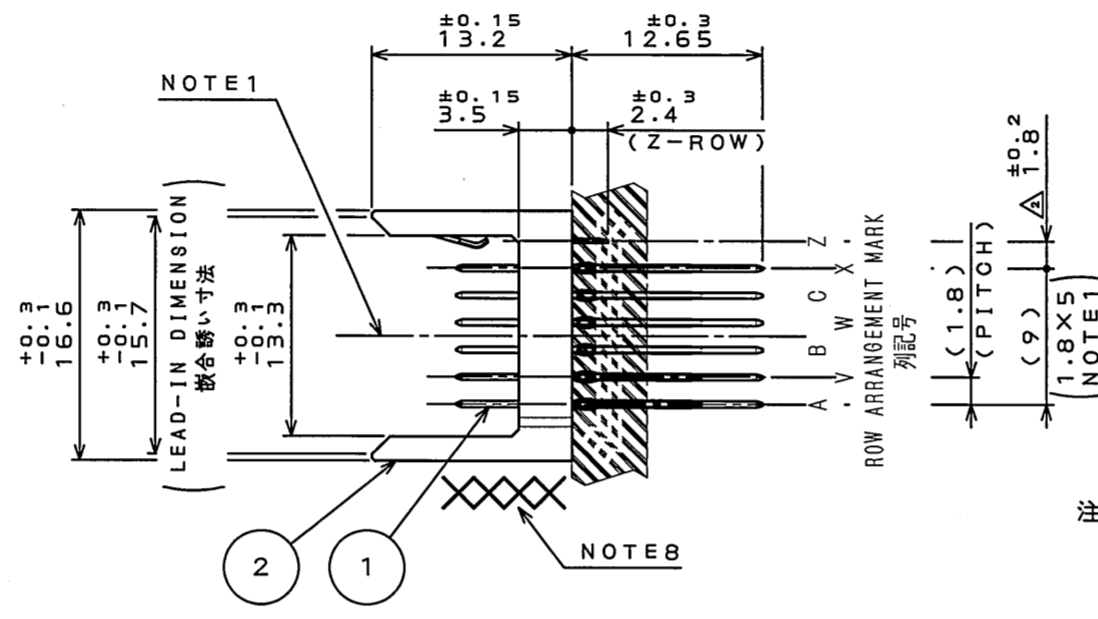
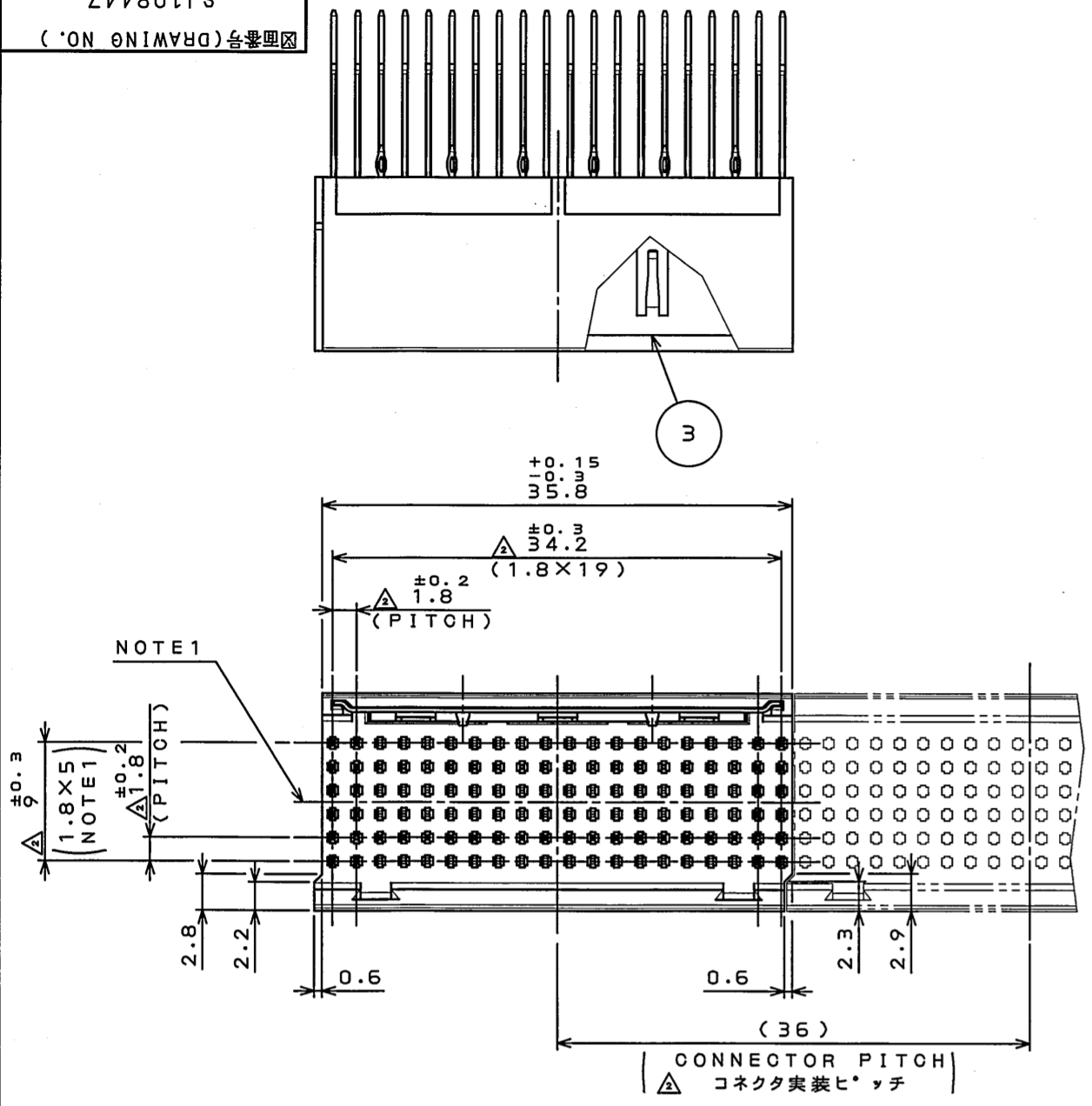
版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	19.May.2009	066789	CHANGED FORM ETC.		Y.ITOU		Y.MIZUSAWA
3	29.Oct.2009	068879	DELETE UL NOTATION.		Y.ITOU		y.mizusawa

NOTE1. THIS LINE IS A CENTERLINE OF TOTAL-PITCH:9 (1.8X5).
 2. TABLE1 SHOWS P.C.B. THROUGH-HOLE SIZE.
 3. : CONNECTOR MOUNTING AREA (FIG.3 REF.).
 4. : THE 6 THROUGH-HOLES IN Z-ROW IS SHORT-CIRCUITED (FIG.3 REF.).
 5. PLATING THICKNESS
 CONTACT AREA : GOLD (0.1 μm MIN.) OVER NICKEL (1.5~5.0 μm) PLATING.
 PRESS-FIT AREA : GOLD (0.03 μm MIN.) OVER NICKEL (1.5~5.0 μm) PLATING.
 6. COMPANY LOGO "JAE" AND PRODUCTION LOT NUMBER AS INDICATED.

(LOT NUMBER DISPLAY EXAMPLE)
 ロット番号表示例) JAE J8528 △
 DAY(01~31)
 生産日表示
 MONTH (RESPECTIVELY OCT:0, NOV:X, DEC:Y)
 月表示(10月:0, 11月:X, 12月:Y)
 YEAR (LAST DIGIT ONLY)
 年表示(百層末尾)
 PRODUCT CODE
 製造コード
 COMPANY LOGO
 社標

7. NOTE IT IN DIRECTION OF THE CONNECTOR (FIG.2 REF.).
 8. : THE GUIDE-WAY SIDE

注1. 寸法9 (1.8X5)の中心線を示す。
 2. スルーホール仕様をTABLE1に示す。
 3. はコネクタ実装領域を示す(FIG.3 参照)。
 4. 内のZ列のスルーホールは、コネクタ構造上同一端子である(FIG.3 参照)。
 5. めっき仕様
 接触部: ニッケル(1.5~5.0 μm)上 金めっき(0.1 μm以上)
 結線部: ニッケル(1.5~5.0 μm)上 金フラッシュめっき(0.03 μm以上)
 6. 図示の位置に社標, ロット番号を表示する。
 7. 図示のガイドに沿って、嵌合すること(FIG.2 参照)。
 8. は、嵌合ガイド側を示す。



MJ06-120MSP-A5-A
 PRODUCT IDENTIFICATION MARK 製品識別記号

APPLICABLE P.C.B THICKNESS 0: FOR t3.5±0.3 AND t5.0±0.4 [mm] 3: FOR t3.5±0.3 [mm] ONLY 5: FOR t5.0±0.4 [mm] ONLY	適合基板厚さ 0: t3.5±0.3, t5.0±0.4 [mm] 3: t3.5±0.3 [mm] 5: t5.0±0.4 [mm]
INSULATOR STYLE A: FOR ANGLE-SOCKET H: FOR HARNESS-SOCKET	インシュレータ形状 A: 対アングソケット H: 対ハーネスソケット
TERMINATION STYLE P: PRESS-FIT H: HARNESS	結線方式 P: プレスフィット H: ハーネス
CONNECTING DIRECTION R: RIGHT-ANGLE S: STRAIGHT	接続方向 R: ライトアング S: ストレート
PRODUCT STYLE F: SOCKET-CONTACT M: PIN-CONTACT S: SHROUD O: HARNESS-CLIP	製品形態 F: ソケットコンタクト M: ピンコンタクト S: シェラウト O: ハーネスクリップ

NUMBER OF CONTACTS 芯数

SERIES シリーズ名

DESIGNATION 命名法

TABLE1 P.C.B. THROUGH-HOLE SIZE (REF.)
 基板スルーホール寸法(参考)

FINISHED HOLE DIAMETER (GOLD OVER COPPER PLATING) 仕上り径(銅上Auフラッシュめっき)	±0.05 φ0.6 [mm]
STARTED DRILL DIAMETER ドリル下穴径	±0.025 φ0.7 [mm]
COPPER PLATING THICKNESS 銅めっき厚	20 [μm] MIN.
P.C.B MATERIAL 基板材料	GLASS FILLED EPOXY ガラス布入りエポキシ積層板

3 SHIELD-PLATE	1 COPPER ALLOY	NOTES	
2 INSULATOR	1 GLASS FILLED PBT		COLOR: WHITE △
1 CONTACT	120 COPPER ALLOY	NOTES	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL
仕様書(SPECIFICATION)	JACS-10524	第1版(ORIGINAL DATE) 28.May.2008	尺(SCALE) 2:1
製図 DR.		製図 CHK.	Y.ITOU
承認 APPD.		承認 APPD.	Y.MIZUSAWA
寸法(DIMENSION)	角度(ANGLES)		
. ±0.8	X° ±		
.X ±0.4	X°X' ±		
.XX ±0.1	X°X'X" ±		
質量(MASS) 8.7[g]		名称(TITLE) MJ06-120MSP-A5-A PIN-HEADER LONG (FOR ANGLE-SOCKET)	
図面番号(DRAWING NO.) SJ108447		日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD. 図面番号(DRAWING NO.) SJ108447	